

# LTM2882

# Y Dual Isolated RS232 µModule Transceiver + Power

## **FEATURES**

- Isolator µModule Technology
- Isolated Dual RS232 Transceiver: 2500V<sub>RMS</sub>
- Integrated Isolated DC/DC Converter: 1W. 65% Efficiency
- No External Components Required
- 1.62V to 5.5V Logic Supply for Flexible Digital Interface
- High Speed Operation 1Mbps for 250pF/3kΩ Load 250kbps for 1nF/3kΩ Load 100kbps for 2.5nF/3kΩ TIA/EIA-232-F Load
- 3.3V (LTM2882-3) or 5V (LTM2882-5) Operation
- No Damage or Latchup to ±10kV ESD HBM on Isolated RS232 Interface or Across Isolation Barrier
- High Common Mode Transient Immunity: 30kV/μs
- Common Mode Working Voltage: 560V<sub>PFAK</sub>
- True RS232 Compliant Output Levels
- Small Low Profile (15mm × 11.25mm × 2.8mm)
  Surface Mount LGA Package

## **APPLICATIONS**

- Isolated RS232 Interface
- Industrial Communication
- www.partesteand.Measurement Equipment
  - Breaking RS232 Ground Loops

## DESCRIPTION

The LTM®2882 is a complete galvanically isolated dual RS232 µModule®transceiver. No external components are required. A single 3.3V or 5V supply powers both sides of the interface through an integrated, isolated DC/DC converter. A logic supply pin allows easy interfacing with different logic levels from 1.62V to 5.5V, independent of the main supply.

Coupled inductors and an isolation power transformer provide  $2500V_{RMS}$  of isolation between the line transceiver and the logic interface. This device is ideal for systems with different grounds, allowing for large common mode voltages. Uninterrupted communication is guaranteed for common mode transients greater than  $30kV/\mu s$ .

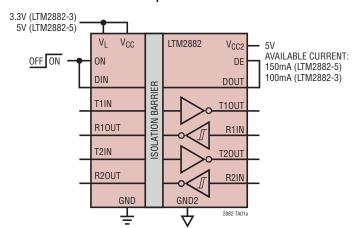
This part is compatible with the TIA/EIA-232-F standard. Driver outputs are protected from overload and can be shorted to ground or up to  $\pm 15V$  without damage. An auxiliary isolated digital channel is available. This channel allows configuration for half-duplex operation by controlling the DE pin.

Enhanced ESD protection allows this part to withstand up to  $\pm 10 \text{kV}$  (human body model) on the transceiver interface pins to isolated supplies and across the isolation barrier to logic supplies without latchup or damage.

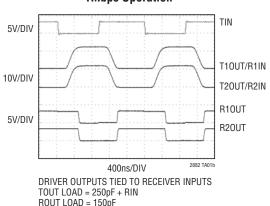
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## TYPICAL APPLICATION

#### Isolated Dual RS232 µModule Transceiver



#### 1Mbps Operation



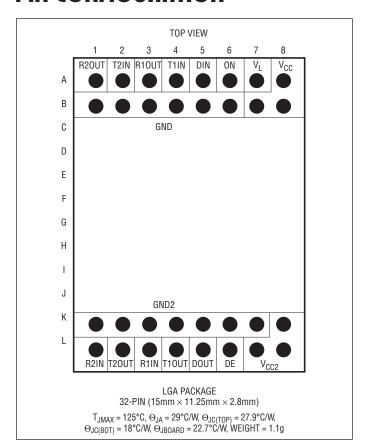
2882p

## **ABSOLUTE MAXIMUM RATINGS**

#### (Note 1)

` ,
$V_{CC}$ to GND0.3V to 6V $V_L$ to GND0.3V to 6V
V <sub>CC2</sub> to GND20.3V to 6V
Logic Inputs
T1IN, T2IN, ON, DIN to GND $-0.3V$ to $(V_L + 0.3V)$
DE to GND2 $-0.3V$ to $(V_{CC2} + 0.3V)$
Logic Outputs
R10UT, R20UT to GND $-0.3V$ to $(V_L + 0.3V)$
DOUT to GND20.3V to $(V_{CC2} + 0.3V)$
Driver Output Voltage
T10UT, T20UT to GND215V to 15V
Receiver Input Voltage
R1IN, R2IN to GND2 –25V to 25V
Operating Temperature Range (Note 4)
$LTM2882C \dots 0^{\circ}C \leq T_{A} \leq 70^{\circ}C$
LTM2882I $-40^{\circ}\text{C} \le T_{A} \le 85^{\circ}\text{C}$
Storage Temperature Range55°C to 125°C
Peak Reflow Temperature (Soldering, 10 sec) 245°C

# PIN CONFIGURATION



# **ORDER INFORMATION**

w.DataSneet4U.com						
LEAD FREE FINISH	TRAY	PART MARKING*	PACKAGE DESCRIPTION	TEMPERATURE RANGE		
LTM2882CV-3#PBF	LTM2882CV-3#PBF	LTM2882V-3	32-Pin (15mm × 11.25mm × 2.8mm) LGA	0°C to 70°C		
LTM2882IV-3#PBF	LTM2882IV-3#PBF	LTM2882V-3	32-Pin (15mm × 11.25mm × 2.8mm) LGA	-40°C to 85°C		
LTM2882CV-5#PBF	LTM2882CV-5#PBF	LTM2882V-5	32-Pin (15mm × 11.25mm × 2.8mm) LGA	0°C to 70°C		
LTM2882IV-5#PBF	LTM2882IV-5#PBF	LTM2882V-5	32-Pin (15mm × 11.25mm × 2.8mm) LGA	-40°C to 85°C		

Consult LTC Marketing for parts specified with wider operating temperature ranges. \*The temperature grade is identified by a label on the shipping container. Consult LTC Marketing for information on lead based finish parts.

For more information on lead free part marking, go to: http://www.linear.com/leadfree/

This product is only offered in trays. For more information go to: http://www.linear.com/packaging/



**ELECTRICAL CHARACTERISTICS** The  $\bullet$  denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25\,^{\circ}C$ . LTM2882-3  $V_{CC} = 3.3V$ , LTM2882-5  $V_{CC} = 5.0V$ ,  $V_L = V_{CC}$ , and GND = GND2 = 0V, ON =  $V_L$  unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Supplies						,	
V <sub>CC</sub>	Input Supply Range	LTM2882-3	•	3.0	3.3	3.6	\
		LTM2882-5	•	4.5	5.0	5.5	\
V <sub>L</sub>	Logic Supply Range		•	1.62		5.5	\
Icc	Input Supply Current	ON = 0V	•		0	10	μA
		LTM2882-3, No Load	•		24	30	m <i>P</i>
		LTM2882-5, No Load	•		17	21	m <i>P</i>
V <sub>CC2</sub>	Regulated Output Voltage, Loaded	LTM2882-3 DE = 0V, I <sub>LOAD</sub> = 100mA	•	4.7	5.0		\
		LTM2882-5 DE = 0V, I <sub>LOAD</sub> = 150mA	•	4.7	5.0		\
V <sub>CC2(NOLOAD)</sub>	Regulated Output Voltage, No Load	DE = 0, No Load		4.8	5.0	5.35	\
	Efficiency	I <sub>CC2</sub> = 100mA, LTM2882-5 (Note 2)			65		%
I <sub>CC2</sub>	Output Supply Short-Circuit Current		•			250	mA
Driver							
$V_{OLD}$	Driver Output Voltage Low	$R_L = 3k\Omega$	•	-5	-5.7		V
$V_{OHD}$	Driver Output Voltage High	$R_L = 3k\Omega$	•	5	6.2		\
I <sub>OSD</sub>	Driver Short-Circuit Current	V <sub>T10UT</sub> , V <sub>T20UT</sub> = 0V, V <sub>CC2</sub> = 5.5V	•		±35	±70	m/
I <sub>OZD</sub>	Driver Three-State (High Impedance) Output Current	DE = 0V, V <sub>T10UT</sub> , V <sub>T20UT</sub> = ±15V	•		±0.1	±10	μA
Receiver	Output Ourrent						
V <sub>IR</sub>	Receiver Input Threshold	Input Low		0.8	1.3		V
VIR	neceiver input riffestiolu	Input High		0.0	1.7	2.5	\
V <sub>HYSR</sub>	Receiver Input Hysteresis	mparriigii		0.1	0.4	1.0	V
R <sub>IN</sub>	Receiver Input Resistance	$-15V \le (V_{R1IN}, V_{R2IN}) \le 15V$	•	3	5	7	kΩ
<u>rin</u> LogieSheet4		-13V \( (VR1IN, VR2IN) \( \) 13V		J	J	ı	
	Logic Input Threshold Voltage	ON, T1IN, T2IN, DIN = 1.62V ≤ V <sub>L</sub> < 2.35V		0.25•V <sub>L</sub>		0.75∙V <sub>L</sub>	\
$V_{ITH}$	Logic input fillesiloid voltage	ON, T1IN, T2IN, DIN = $1.62 \text{V} \le \text{V}_{\text{L}} < 2.33 \text{V}$ ON, T1IN, T2IN, DIN = $2.35 \text{V} \le \text{V}_{\text{I}} \le 5.5 \text{V}$		0.25•VL		0.75•VL 0.67•V <sub>I</sub>	\ \
		DE		0.4		0.67•V <sub>CC2</sub>	V
I	Logic Input Current	DE		0.4		±1	μ.Α
I <sub>INL</sub>	Logic Input Hysteresis	T1IN, T2IN, DIN (Note 2)			150	Ξ1	μ <i>-</i> m\
V <sub>HYS</sub>	Logic Output High Voltage	R10UT, R20UT			130		1111
V <sub>OH</sub>	Logic Output riigii Voltage	$I_{LOAD} = -1$ mA (Sourcing), $1.62$ V $\leq$ V <sub>L</sub> $< 3.0$ V $I_{LOAD} = -4$ mA (Sourcing), $3.0$ V $\leq$ V <sub>L</sub> $\leq 5.5$ V	•	V <sub>L</sub> - 0.4 V <sub>L</sub> - 0.4			\
		DOUT, I <sub>LOAD</sub> = -4mA (Sourcing)	•	V <sub>CC2</sub> - 0.4			\
V <sub>OL</sub>	Logic Output Low Voltage	R10UT, R20UT $I_{LOAD} = 1$ mA (Sinking), 1.62V $\leq$ V <sub>L</sub> $<$ 3.0V		002		0.4	V
		$I_{LOAD} = 4mA \text{ (Sinking)}, 3.0V \le V_L \le 5.5V$	•			0.4	\
		DOUT, I <sub>LOAD</sub> = 4mA (Sinking)	•			0.4	\
ESD (HBM) (N						Г	
	RS232 Driver and Receiver Protection	(T10UT, T20UT, R1IN, R2IN) to (V <sub>CC2</sub> , GND2)			±10		k۱
		(T10UT, T20UT, R1IN, R2IN) to (V <sub>CC</sub> , V <sub>L</sub> , GND)			±10		k۱
	Isolation Boundary	(V <sub>CC2</sub> , GND2) to (V <sub>CC</sub> , V <sub>L</sub> , GND)			±10		kV



**SWITCHING CHARACTERISTICS** The  $\bullet$  denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^{\circ}C$ . LTM2882-3  $V_{CC} = 3.3V$ , LTM2882-5  $V_{CC} = 5.0V$ ,  $V_L = V_{CC}$ , and GND = GND2 = 0V, ON =  $V_L$  unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
	Maximum Data Rate	$R_L = 3k\Omega$ , $C_L = 2.5nF$ (Note 3)	•	100			kbps
(T1IN to T10UT, T2IN to T20UT)	$R_L = 3k\Omega$ , $C_L = 1nF$ (Note 3)	•	250			kbps	
		$R_L = 3k\Omega$ , $C_L = 250pF$ (Note 3)	•	1000			kbps
	Maximum Data Rate (DIN to DOUT)	C <sub>L</sub> = 15pF	•	10			Mbps
Driver							
	Driver Slew Rate (6V/t <sub>THL</sub> or t <sub>TLH</sub> )	$R_L = 3k\Omega$ , $C_L = 50pF$ (Figure 1)	•			150	V/µs
t <sub>PHLD</sub> , t <sub>PLHD</sub>	Driver Propagation Delay	$R_L = 3k\Omega$ , $C_L = 50pF$ (Figure 1)	•		0.2	0.5	μs
t <sub>SKEWD</sub>	Driver Skew  t <sub>PHLD</sub> - t <sub>PLHD</sub>	$R_L = 3k\Omega$ , $C_L = 50pF$ (Figure 1)			40		ns
t <sub>PZHD</sub> , t <sub>PZLD</sub>	Driver Output Enable Time	DE = $\uparrow$ , R <sub>L</sub> = 3k $\Omega$ , C <sub>L</sub> = 50pF (Figure 2)	•		0.6	2	μs
t <sub>PHZD</sub> , t <sub>PLZD</sub>	Driver Output Disable Time	DE = $\downarrow$ , R <sub>L</sub> = 3k $\Omega$ , C <sub>L</sub> = 50pF (Figure 2)	•		0.3	2	μs
Receiver			•				
t <sub>PHLR</sub> , t <sub>PLHR</sub>	Receiver Propagation Delay	C <sub>L</sub> = 150pF (Figure 3)	•		0.2	0.4	μs
tskewr	Receiver Skew  t <sub>PHLR</sub> - t <sub>PLHR</sub>	C <sub>L</sub> = 150pF (Figure 3)			40		ns
t <sub>RR</sub> , t <sub>FR</sub>	Receiver Rise or Fall Time	C <sub>L</sub> = 150pF (Figure 3)	•		60	200	ns
<b>Auxiliary Chan</b>	nel						
t <sub>PHLL</sub> , t <sub>PLHL</sub>	Propagation Delay	$C_L = 15pF$ , $t_R$ and $t_F < 4ns$ (Figure 4)	•		60	100	ns
t <sub>RL</sub> , t <sub>FL</sub>	Rise or Fall Time	C <sub>L</sub> = 150pF (Figure 4)	•		60	200	ns
Power Supply			•				
	Power-Up Time	ON = ↑ to V <sub>CC2(MIN)</sub>	•		0.2	2	ms

**ISOLATION CHARACTERISTICS** The  $\bullet$  denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^{\circ}C$ . LTM2882-3  $V_{CC} = 3.3V$ , LTM2882-5  $V_{CC} = 5.0V$ ,  $V_L = V_{CC}$ , and GND =  $V_C = V_C = V_C$ 

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
V <sub>ISO</sub> Rated Dielectric Insulation V	Rated Dielectric Insulation Voltage 1 Minute, Derived fro	1 Minute, Derived from 1 Second Test	2500			V <sub>RMS</sub>
		1 Second	±4400			V
	Common Mode Transient Immunity	(Note 2)	30			kV/μs
V <sub>IORM</sub>	Maximum Working Insulation Voltage	(Note 2)	560			V <sub>PEAK</sub>
	Partial Discharge	V <sub>PR</sub> = 1050 V <sub>PEAK</sub> (Note 2)			<5	pC
	Input to Output Resistance	(Note 2)	>10 <sup>9</sup>			Ω
	Input to Output Capacitance	(Note 2)		6		pF
	Creepage Distance	(Note 2)		9.48		mm

**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

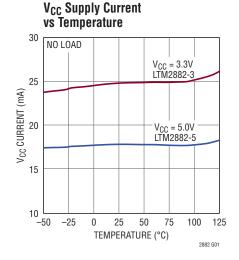
Note 2: Guaranteed by design and not subject to production test.

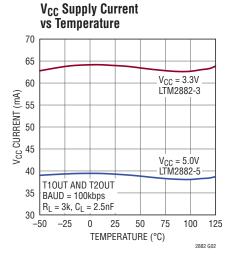
**Note 3:** Maximum Data Rate is guaranteed by other measured parameters and is not tested directly.

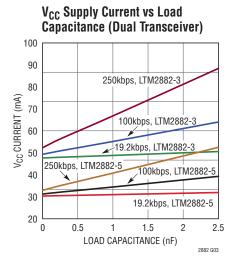
**Note 4:** This device includes over-temperature protection that is intended to protect the device during momentary overload conditions. Junction temperature will exceed 125°C when overtemperature protection is active. Continuous operation above specified maximum operating junction temperature may result in device degradation or failure.

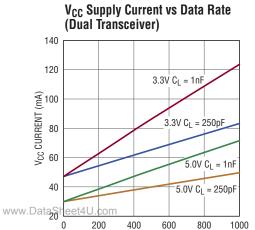
LINEAR

# **TYPICAL PERFORMANCE CHARACTERISTICS** $T_A=25^{\circ}C$ , LTM2882-3 $V_{CC}=3.3V$ , LTM2882-5 $V_{CC}=5V$ , $V_L=3.3V$ , and GND = GND2 = 0V, ON = $V_L$ unless otherwise noted.



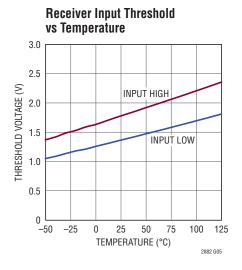


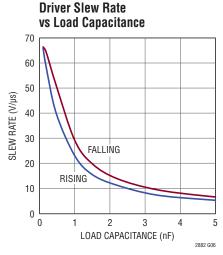


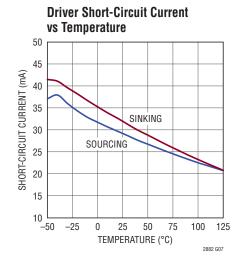


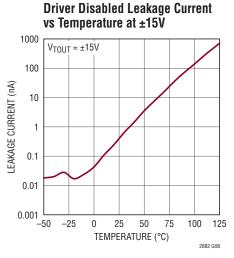
DATA RATE (kbps)

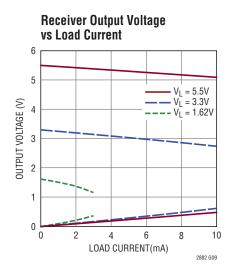
2882 G04



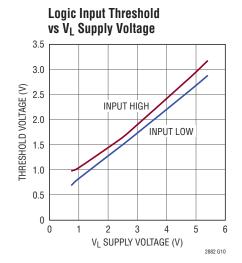






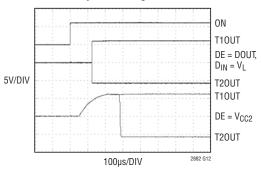


# **TYPICAL PERFORMANCE CHARACTERISTICS** $T_A = 25^{\circ}C$ , LTM2882-3 $V_{CC} = 3.3V$ , LTM2882-5 $V_{CC} = 5V$ , $V_L = 3.3V$ , and GND = GND2 = 0V, ON = $V_L$ unless otherwise noted.



#### V<sub>CC2</sub> Output Voltage vs Load Current V<sub>CC</sub> = 3.0V TO 3.6V, LTM2882-3 V<sub>CC</sub> = 4.5V TO 5.5V, LTM2882-5 5.1 V<sub>CC2</sub> VOLTAGE (V) 7:00 V 5.5V 5.0V 3.3V 3.0\ 4.7 3.6V 4.5V 4.6 4.5 50 150 200 250 300 100

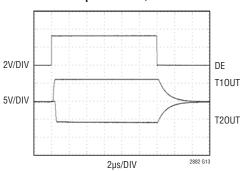
#### **Driver Outputs Exiting Shutdown**



#### **Driver Outputs Enable/Disable**

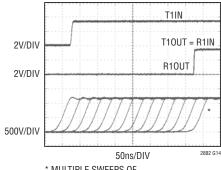
LOAD CURRENT (mA)

2882 G11



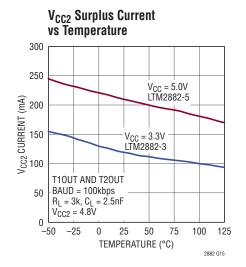
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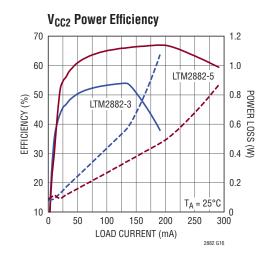
#### Operating Through 35kV/µs **Common Mode Transients**



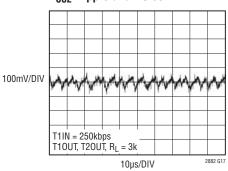
\* MULTIPLE SWEEPS OF COMMON MODE TRANSIENTS

# **TYPICAL PERFORMANCE CHARACTERISTICS** $T_A=25^{\circ}C$ , LTM2882-3 $V_{CC}=3.3V$ , LTM2882-5 $V_{CC}=5V$ , $V_L=3.3V$ , and GND = GND2 = 0V, ON = $V_L$ unless otherwise noted.

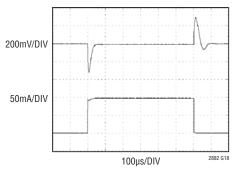




#### V<sub>CC2</sub> Ripple and Noise



## V<sub>CC2</sub> Load Step Response



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## **TEST CIRCUITS**

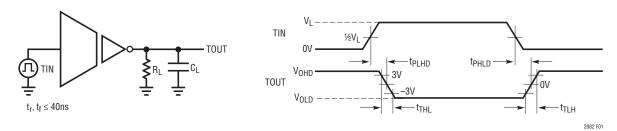


Figure 1. Driver Slew Rate and Timing Measurement

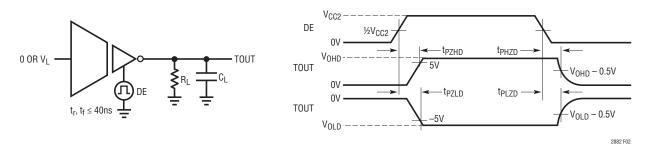


Figure 2. Driver Enable/Disable Times

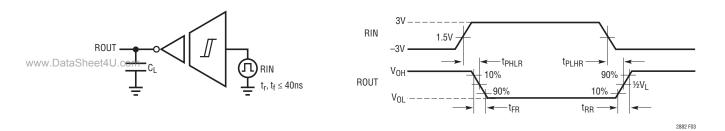


Figure 3. Receiver Timing Measurement

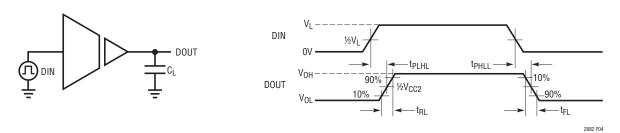


Figure 4. Auxiliary Channel Timing Measurement

LINEAR

## PIN FUNCTIONS

#### **LOGIC SIDE**

**R20UT (Pin A1):** Channel 2 RS232 Inverting Receiver Output. Controlled through isolation barrier from receiver input R2IN. Under the condition of an isolation communication failure R2OUT is in a high impedance state.

**T2IN (Pin A2):** Channel 2 RS232 Inverting Driver Input. A logic low on this input generates a high on isolated output T2OUT. A logic high on this input generates a low on isolated output T2OUT. Do not float.

**R10UT (Pin A3):** Channel 1 RS232 Inverting Receiver Output. Controlled through isolation barrier from receiver input R1IN. Under the condition of an isolation communication failure R10UT is in a high impedance state.

**T1IN (Pin A4):** Channel 1 RS232 Inverting Driver Input. A logic low on this input generates a high on isolated output T10UT. A logic high on this input generates a low on isolated output T10UT. Do not float.

**DIN (Pin A5):** General Purpose Non-Inverting Logic Input. A logic high on DIN generates a logic high on isolated output DOUT. A logic low on DIN generates a logic low on isolated output DOUT. Do not float.

**ON (Pin A6):** Enable. Enables power and data communication through the isolation barrier. If ON is high the part is enabled and power and communications are functional to the isolated side. If ON is low the logic side is held in reset and the isolated side is unpowered. Do not float.

**V<sub>L</sub>** (**Pin A7**): Logic Supply. Interface supply voltage for pins DIN, R2OUT, T2IN, R1OUT, T1IN, and ON. Operating voltage is 1.62V to 5.5V.

**V<sub>CC</sub>** (**Pins A8, B7-B8**): Supply Voltage. Operating voltage is 3.0V to 3.6V for LTM2882-3, and 4.5V to 5.5V for LTM2882-5.

GND (Pins B1-B6): Circuit Ground.

#### **ISOLATED SIDE**

**GND2 (Pins K1-K7):** Isolated Side Circuit Ground. These pads should be connected to the isolated ground and/or cable shield.

 $V_{CC2}$  (Pins K8, L7-L8): Isolated Supply Voltage Output. Internally generated from  $V_{CC}$  by an isolated DC/DC converter and regulated to 5V. Supply voltage for pins R1IN, R2IN, DE, and DOUT.

**R2IN (Pin L1):** Channel 2 RS232 Inverting Receiver Input. A low on isolated input R2IN generates a logic high on R2OUT. A high on isolated input R2IN generates a logic low on R2OUT. Impedance is nominally  $5k\Omega$  in receive mode or unpowered.

**T20UT (Pin L2):** Channel 2 RS232 Inverting Driver Output. Controlled through isolation barrier from driver input T2IN. High impedance when the driver is disabled (DE pin is low).

**R1IN (Pin L3):** Channel 1 RS232 Inverting Receiver Input. A low on isolated input R1IN generates a logic high on R10UT. A high on isolated input R1IN generates a logic low on R10UT. Impedance is nominally  $5k\Omega$  in receive mode or unpowered.

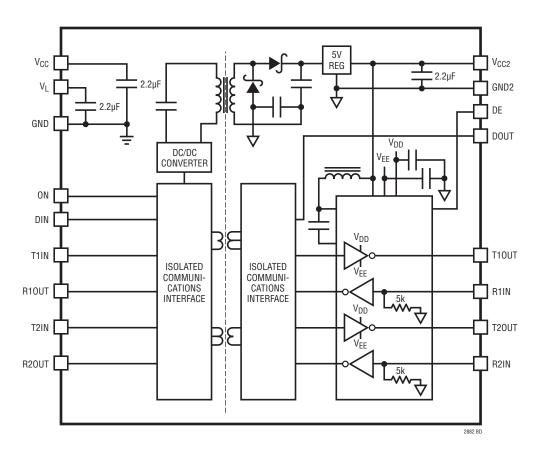
**T10UT (Pin L4):** Channel 1 RS232 Inverting Driver Output. Controlled through isolation barrier from driver input T1IN. High impedance when the driver is disabled (DE pin is low).

**DOUT (Pin L5):** General Purpose Non-Inverting Logic Output. Logic output connected through isolation barrier to DIN.

**DE (Pin L6):** Driver Output Enable. A low input forces both RS232 driver outputs, T10UT and T20UT, into a high impedance state. A high input enables both RS232 driver outputs. Do not float.



# **BLOCK DIAGRAM**



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## APPLICATIONS INFORMATION

#### **Overview**

The LTM2882 µModule transceiver provides a galvanically-isolated robust RS232 interface, powered by an integrated, regulated DC/DC converter, complete with decoupling capacitors. The LTM2882 is ideal for use in networks where grounds can take on different voltages. Isolation in the LTM2882 blocks high voltage differences, eliminates ground loops and is extremely tolerant of common mode transients between grounds. Error-free operation is maintained through common mode events greater than 30kV/µs providing excellent noise isolation.

#### µModule Technology

The LTM2882 utilizes isolator  $\mu$ Module technology to translate signals and power across an isolation barrier. Signals on either side of the barrier are encoded into pulses and translated across the isolation boundary using coreless transformers formed in the  $\mu$ Module substrate. This system, complete with data refresh, error checking, safe shutdown on fail, and extremely high common mode immunity, provides a robust solution for bidirectional signal isolation. The  $\mu$ Module technology provides the means to combine the isolated signaling with our advanced dual RS232 transceiver and powerful isolated DC/DC converter in one small package.

#### \*\*\*\*DC/DC Converter

The LTM2882 contains a fully integrated isolated DC/DC converter, including the transformer, so that no external components are necessary. The logic side contains a full-bridge driver, running at about 2MHz, and is AC-coupled to a single transformer primary. A series DC blocking capacitor prevents transformer saturation due to driver duty cycle imbalance. The transformer scales the primary voltage, and is rectified by a full-wave voltage doubler. This topology eliminates transformer saturation caused by secondary imbalances.

The DC/DC converter is connected to a low dropout regulator (LDO) to provide a regulated low noise 5V output,  $V_{CC2}$ .

An integrated boost converter generates a 7V  $V_{DD}$  supply and a charge pumped -6.3V  $V_{EE}$  supply.  $V_{DD}$  and  $V_{EE}$  power the output stage of the RS232 drivers and are regulated to levels that guarantee greater than  $\pm 5V$  output swing.

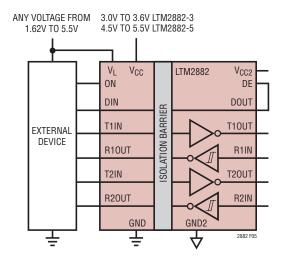


Figure 5. V<sub>CC</sub> and V<sub>L</sub> Are Independent

The internal power solution is sufficient to support the transceiver interface at its maximum specified load and data rate, and has the capacity to provide additional 5V power on the isolated side  $V_{CC2}$  and GND2 pins.  $V_{CC}$  and  $V_{CC2}$  are each bypassed internally with 2.2 $\mu$ F ceramic capacitors.

#### **V<sub>L</sub>** Logic Supply

A separate logic supply pin  $V_L$  allows the LTM2882 to interface with any logic signal from 1.62V to 5.5V as shown in Figure 5. Simply connect the desired logic supply to  $V_L$ .

There is no interdependency between  $V_{CC}$  and  $V_L$ ; they may simultaneously operate at any voltage within their specified operating ranges and sequence in any order.  $V_L$  is bypassed internally by a  $2.2\mu F$  capacitor.

## **Hot Plugging Safely**

Caution must be exercised in applications where power is plugged into the LTM2882's power supplies,  $V_{CC}$  or  $V_L$ , due to the integrated ceramic decoupling capacitors. The parasitic cable inductance along with the high Q characteristics of ceramic capacitors can cause substantial ringing which could exceed the maximum voltage ratings and damage the LTM2882. Refer to Linear Technology Application Note 88, entitled "Ceramic Input Capacitors Can Cause Overvoltage Transients" for a detailed discussion and mitigation of this phenomenon.



# APPLICATIONS INFORMATION

### **Channel Timing Uncertainty**

Multiple channels are supported across the isolation boundary by encoding and decoding of the inputs and outputs. The technique used assigns T1IN/R1IN the highest priority such that there is no jitter on the associated output channels T10UT/R10UT, only delay. This preemptive scheme will produce a certain amount of uncertainty on T2IN/R2IN to T20UT/R20UT and DIN to D0UT. The resulting pulse width uncertainty on these low priority channels is typically  $\pm 6$ ns, but may vary up to about 40ns.

## **Half-Duplex Operation**

The DE pin serves as a low-latency driver enable for half-duplex operation. The DE pin can be easily driven from the logic side by using the uncommitted auxiliary digital channel, DIN to DOUT. Each driver is enabled and disabled in less than 2µs, while each receiver remains continuously active. This mode of operation is illustrated in Figure 6.

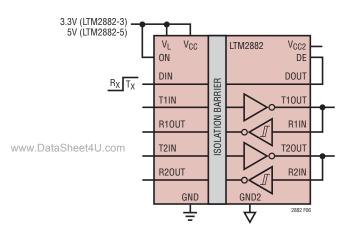


Figure 6. Half-Duplex Configuration Using  $\mathbf{D}_{\text{OUT}}$  to Drive DE

#### **Driver Overvoltage and Overcurrent Protection**

The driver outputs are protected from short-circuits to any voltage within the absolute maximum range of ±15V relative to GND2. The maximum current is limited to no more than 70mA to maintain a safe power dissipation and prevent damaging the LTM2882.

## **Receiver Overvoltage and Open Circuit**

The receiver inputs are protected from common mode voltages of ±25V relative to GND2.

Each receiver input has a nominal input impedance of  $5k\Omega$  relative to GND2. An open circuit condition will generate a logic high on each receiver's respective output pin.

#### **RF**, Magnetic Field Immunity

The LTM2882 has been independently evaluated and has successfully passed the RF and magnetic field immunity testing requirements per European Standard EN 550024, in accordance with the following test standards:

EN 61000-4-3	Radiated, Radio-Frequency, Electromagnetic Field Immunity
EN 61000-4-8	Power Frequency Magnetic Field Immunity

EN 61000-4-9 Pulsed Magnetic Field Immunity

Tests were performed using an unshielded test card designed per the data sheet PCB layout recommendations. Specific limits per test are detailed in Table 1.

Table 1

TEST	FREQUENCY	FIELD STRENGTH
EN 61000-4-3, Annex D	80MHz to 1GHz	10V/m
	1.4MHz to 2GHz	3V/m
	2GHz to 2.7GHz	1V/m
EN61000-4-8, Level 4	50Hz and 60Hz	30A/m
EN61000-4-8, Level 5	60Hz	100A/m*
EN61000-4-9, Level 5	Pulse	1000A/m

<sup>\*</sup>Non IEC Method



## APPLICATIONS INFORMATION

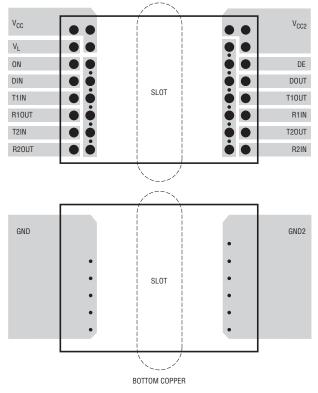
## **PCB** Layout

The high integration of the LTM2882 makes PCB layout very simple. However, to optimize its electrical isolation characteristics, EMI, and thermal performance, some layout considerations are necessary. Figure 7 is a suggested layout for good thermal performance and to optimize isolation characteristics.

- Under heavily loaded conditions, the current in V<sub>CC</sub> and GND can exceed 300mA. PCB copper must be made wide enough in these paths to ensure resistive losses do not cause the supply voltage at the LTM2882 to drop below the minimum allowed levels. Similarly, the metal in the V<sub>CC2</sub> and GND2 must be wide enough to support any external load connected.
- Input and output decoupling is not required, since these components are integrated within the package. If additional capacitance is used, place as close to the power and ground terminals as possible to minimize high frequency noise. For EMI sensitive applications, an additional low ESR capacitance of 6.8µF to 22µF is recommended from V<sub>CC</sub> to GND.

- Do not place copper on the PCB between the inner columns of pads. This area must remain open to withstand the rated isolation voltage. The PCB may also be slotted in this area to facilitate cleaning and ensure contamination does not compromise the isolation voltage.
- The recommended layout of Figure 7 shows copper planes for GND and GND2, which is good practice to optimize signal fidelity and minimize emissions on either side of the isolation boundary. However, this creates a dipole antenna which can radiate differential voltages formed between GND and GND2. A small capacitance (<200pF) from GND to GND2, either discrete or embedded within the substrate, provides a low impedance path minimizing the high frequency differential voltages and substantially reducing radiated emissions. Care should be exercised in applying these techniques to insure the voltage rating of the isolation barrier is not compromised.

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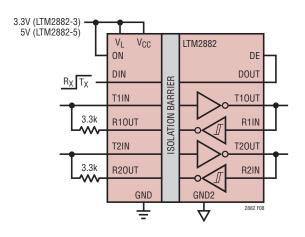


TOP COPPER

Figure 7. Recommended PCB Layout



## TYPICAL APPLICATIONS



3.3V (LTM2882-3) 5V (LTM2882-5) LTM2882  $V_L$  $V_{CC}$ ON DE DIN DOUT ISOLATION BARRIER T1IN T10UT R10UT R1IN T2IN T20UT R20UT R2IN DATA RATE GND (kbps) C<sub>L</sub> (nF) 2882 F09 100 5 250 2 1000 0.5

Figure 8. Single Line Dual Half-Duplex Isolated Transceiver

Figure 9. Driving Larger Capacitive Loads

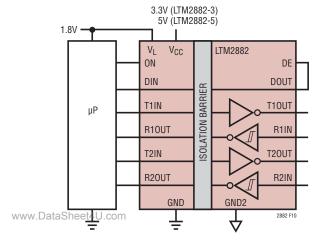


Figure 10. 1.8V Microprocessor Interface

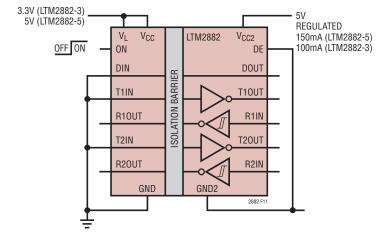


Figure 11. Isolated 5V Power Supply

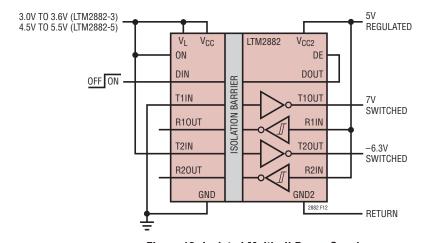
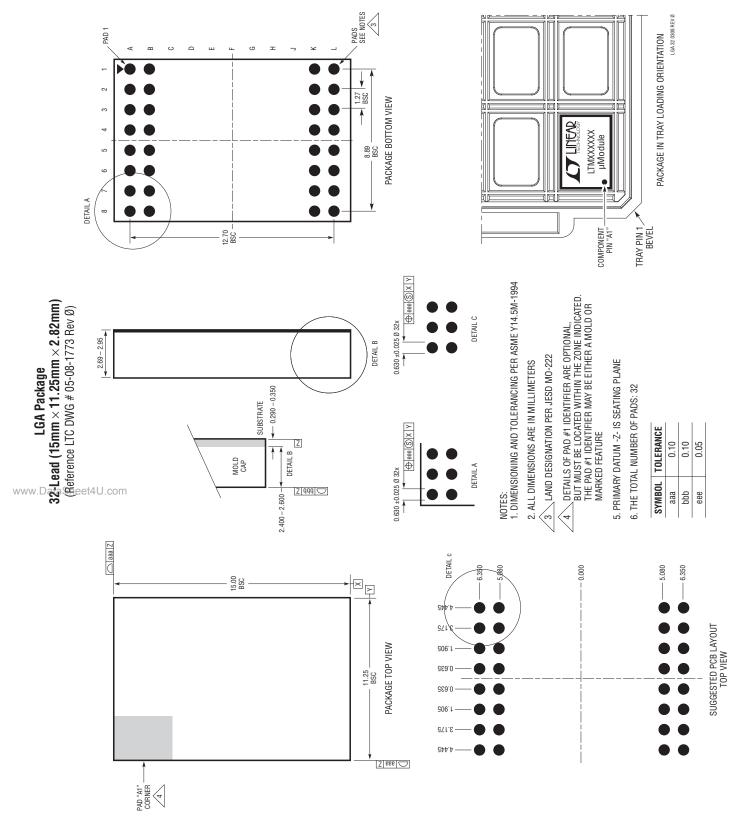


Figure 12. Isolated Multirail Power Supply with Switched Outputs



## PACKAGE DESCRIPTION



## TYPICAL APPLICATIONS

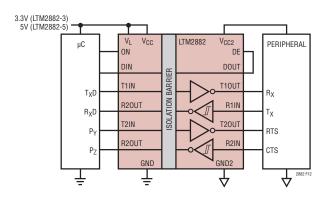


Figure 13. Isolated RS232 Interface with Handshaking

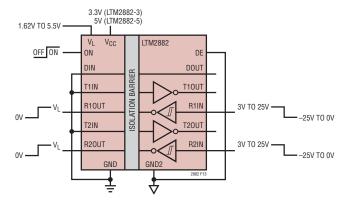
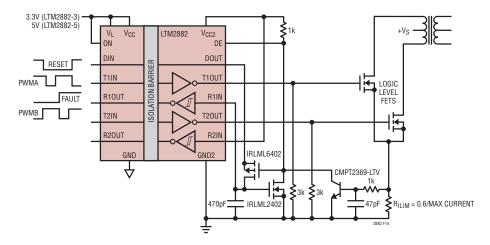


Figure 14. Isolated Dual Inverting Level Translator



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Figure 15. Isolated Gate Drive with Overcurrent Detection

# **RELATED PARTS**

PART NUMBER	DESCRIPTION	COMMENTS
LTM2881	Isolated RS485/RS422 µModule Transceiver with Integrated DC/DC Converter	20Mbps, 15kV HBM ESD, 2500V <sub>RMS</sub> Isolation with Power
LTC2804	1Mbps RS232 Transceiver	Dual Channel, Full-Duplex, 10kV HBM ESD
LTC1535	Isolated RS485 Transceiver	2500 V <sub>RMS</sub> Isolation with External Transformer Driver